

WHAT IS CLAIMED IS:

1. A semiconductor mechanical sensor comprising:
a semiconductor substrate;
a beam structure extending in spaced relation over said semiconductor substrate;
a weight connected to said beam structure and including a first mechanical force detect electrode, said weight being movable along a predetermined direction;
a second mechanical force detect electrode facing said first mechanical force detect electrode of said weight;
an oscillation member for oscillating said weight; and
a sense electrode detecting oscillation of said weight for feedback control of oscillation of said weight;
wherein movement of said weight produces a change in capacitance between said first mechanical force detect electrode and said second mechanical force detect electrode to enable said sensor to detect mechanical forces acting thereon.
2. A semiconductor mechanical sensor in accordance with claim 1, wherein said oscillation member includes a third electrode and a fourth electrode, said third electrode being formed on said weight and said fourth electrode facing said third electrode.
3. A semiconductor mechanical sensor in accordance with claim 1, which is adapted to be used as a yaw rate sensor.
4. A semiconductor mechanical sensor in accordance with claim 2, wherein said sense electrode and said fourth electrode are formed on the same plane.

5. A semiconductor mechanical sensor in accordance with claim 1, wherein said oscillation member oscillates said weight in a direction generally perpendicular to said predetermined direction.

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